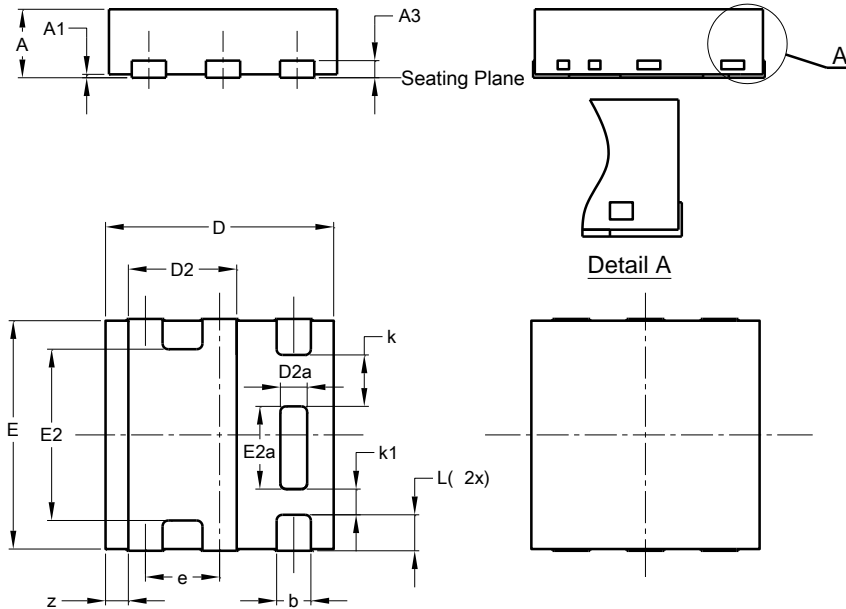


**Package Outline Dimensions**

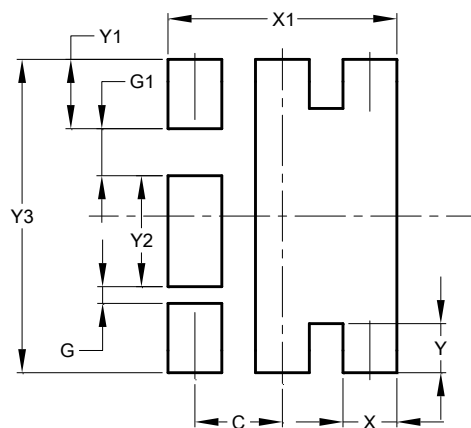
U-DFN2020-6/SWP



U-DFN2020-6/SWP			
Dim	Min	Max	Typ
A	0.59	0.65	0.62
A1	0	0.05	0.03
A3	-	-	0.19
b	0.28	0.38	0.33
D	1.95	2.05	2.00
D2	0.87	1.07	0.97
D2a	0.205	0.305	0.255
E	1.95	2.05	2.00
E2	1.42	1.62	1.52
E2a	0.69	0.79	0.74
e	0.65 BSC		
L	0.28	0.38	0.33
k	0.450 BSC		
k1	0.225 BSC		
Z	-	-	0.20
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

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Dimensions	Value (in mm)
C	0.650
G	0.125
G1	0.350
X	0.400
X1	1.700
Y	0.365
Y1	0.515
Y2	0.825
Y3	2.330

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.